

Attorney Docket No. 01470/LH

**IN THE UNITED STATES PATENT
AND TRADEMARK OFFICE**

Applicant(s): I. TAHARA et al

Serial No. :

Filed : Herewith

For : SEMICONDUCTOR
DEVICE

Art Unit :
Examiner :

INFORMATION DISCLOSURE STATEMENT

Asst. Commissioner for Patents
Washington, D.C. 20231

S I R :

Submitted herewith are copies of the publications identified on the attached Patent Office form PTO/SB/08A.

It is respectfully requested that these publications be considered and made of record.

DISCUSSION

Japanese No. 5-218042 discloses a semiconductor device having an element forming area and bump electrodes formed on second bonding pads positioned on the inside of first bonding pads. The bump electrodes are respectively connected to terminal electrodes formed on a substrate.

CROSS-REFERENCE TO RELATED APPLICATION

Listed below is a copending application which is related to the present application:

Express Mail Mailing Label
No.: EL 797 383 446 US

Date of Deposit: August 8, 2001

I hereby certify that this paper is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to the Asst. Commissioner for Patents, Washington, D.C. 20231

Barbara Villani
Barbara Villani

In the event that this Paper is late filed, and the necessary petition for extension of time is not filed concurrently herewith, please consider this as a Petition for the requisite extension of time, and to the extent not tendered by check attached hereto, authorization to charge the extension fee, or any other fee required in connection with this Paper to Account No. 06-1378.

1c872 U.S. PRO
09/924293

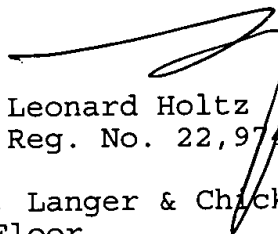


1-18-02
PB

1. U.S. Serial No. 09/499,599 filed February 7, 2000 (COPY
OF ENTIRE APPLICATION ATTACHED).

It is respectfully requested that the Examiner consider the
copending related application identified above when considering
the present application on the merits.

Respectfully submitted,



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